DATA SHEET

RC01/02H/21/22H 1%; 5% Chip resistors with Au-terminations sizes 1206 and 0603

Product specification Supersedes data of 27th April 2001 2001 Oct 14 Rev.4



Phycomp Product specification

Chip resistors with Au-terminations sizes 1206 and 0603

RC01/02H/21/22H 1%; 5%

FEATURES

- · Reduced size of final equipment
- · Low assembly costs
- Higher component and equipment reliability
- New Ni/Au terminations provide special application for hybrid board gluing and can replace AgPd terminations.

APPLICATIONS

- · Power supply in small equipment
- · Digital multi-meter
- Telecommunication
- Computer
- Automotive industry.

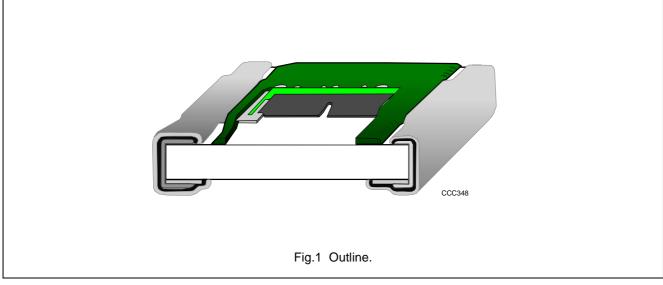
DESCRIPTION

The resistors are constructed on a high grade ceramic body (aluminium oxide). Internal metal electrodes are added at each end and connected by a resistive paste which is applied to the top surface of the substrate. The composition of the paste is adjusted to give the approximate resistance required and the value is trimmed to within tolerance, by laser cutting of this resistive layer.

To ensure the product insulation and performance, the protective overcoat layer is printed upon the resistor layer. Finally, the two external end terminations are added. For ease of soldering the outerlayer of these end terminations is of Ni-Au alloy.

QUICK REFERENCE DATA

DESCRIPTION		VALUE				
DESCRIPTION	RC01	RC02H	RC21	RC22H		
Size code	12	206	06	03		
Resistance range	1 Ω to 10 MΩ					
Resistance tolerance and E-series	±5%; E24 series	±1%; E24/E96 series	±5%; E24 series	±1%; E96 series		
Temperature coefficient:						
$1 \Omega \le R \le 10 \Omega$	250 ±250	250 ±250	250 ±250	250 ±250		
$10 \Omega < R \le 10 M\Omega$	≤±200	≤±100	≤±200	≤±100		
Maximum dissipation at T _{amb} = 70 °C	0.25 W		0.063 W			
Maximum permissible voltage	200 V (D	C or RMS)	50 V (DC or RMS)			
Climatic category (IEC 60068)	55/155/56					
Basic specification		IEC 60	115-8			



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ORDERING INFORMATION

Table 1 Ordering code indicating type and packing

			ORDERING CODE 2322 PAPER TAPE ON REEL 5000 units 10000 units 711 11 –	
TYPE	RESISTANCE VALUE	TOLERANCE (%)	PAPER TAF	PE ON REEL
	77.202	(70)	5000 units	10000 units
RC01	1 Ω to 10 MΩ	±5	711 11	-
RC02H	1 Ω to 10 M Ω	±1	729 1	_
RC21	1 Ω to 10 M Ω	±5	702 11	702 12
RC22H	1 Ω to 10 M Ω	±1	704 1	_

Ordering code (12NC)

- The resistors have a 12-digit ordering code starting with 2322.
- The subsequent 5 digits indicate the resistor type and packing; see Table 1.
- The remaining 3 or 4 digits indicate the resistance value:
 - The first 2 or 3 digits indicate the resistance value.
 - The last digit indicates the resistance decade in accordance with Table 2.

Table 2 Last digit of 12NC

RESISTANCE DECADE	LAST DIGIT
1 to 9.76 Ω	8
10 to 97.6 Ω	9
100 to 976 Ω	1
1 to 976 kΩ	2
10 to 97.6 kΩ	3
100 to 976 kΩ	4
1 to 9.76 MΩ	5
10 MΩ	6

ORDERING EXAMPLE

The ordering code of a RC01 resistor, Au-termination, value 1000 Ω , 5%, supplied on paper tape of 5000 units per reel is: 2322 711 11102.

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FUNCTIONAL DESCRIPTION

Product characterization

Standard values of nominal resistance are taken from the E24 series or E96 series for resistors with a tolerance of $\pm 5\%$ or $\pm 1\%$. The values of the E24/96 series are in accordance with "IEC publication 60063".

Limiting values

TYPE	LIMITING VOLTAGE ⁽¹⁾ (V)	LIMITING POWER (W)
RC01	200	0.25
RC02H	200	0.25
RC21	50	0.063
RC22H	50	0.063

Note

 This is the maximum voltage that may be continuously applied to the resistor element, see "IEC publication 60115-8".

DERATING

The power that the resistor can dissipate depends on the operating temperature; see Fig.2.

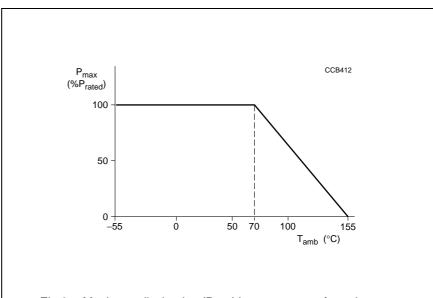


Fig.2 Maximum dissipation (P_{max}) in percentage of rated power as a function of the ambient temperature (T_{amb}).

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MEMOHASNICAL DATA

Mass per 100 units

TYPE	MASS (g)
RC01	1.0
RC02H	1.0
RC21	0.25
RC22H	0.25

Marking

There is no marking on all the products with gold terminations.

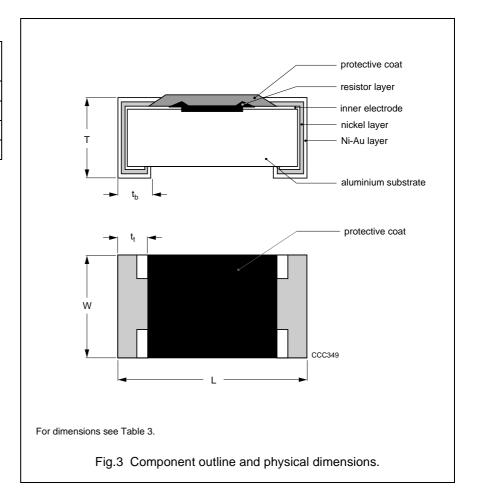


Table 3 Chip resistor types and relevant physical dimensions; see Fig.3

TYPE	L (mm)	W (mm)	T (mm)	t _t (mm)	t _b (mm)
RC01	3.20 +0.10/-0.20	1.60 ±0.15	0.55 ±0.10	0.45 ±0.25	0.50 ±0.25
RC02H	3.20 +0.10/-0.20	1.60 ±0.15	0.55 ±0.10	0.45 ±0.25	0.50 ±0.25
RC21	1.60 ±0.10	0.80 +0.15/-0.05	0.45 ±0.10	0.30 ±0.20	0.30 ±0.20
RC22H	1.60 ±0.10	0.80 +0.15/-0.05	0.45 ±0.10	0.30 ±0.20	0.30 ±0.20

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TESTS AND REQUIREMENTS

Essentially all tests are carried out in accordance with the schedule of "IEC publication 60115-8", category LCT/UCT/56 (rated temperature range: Lower Category Temperature, Upper Category Temperature; damp heat, long term, 56 days). The testing also covers the requirements specified by EIA and EIAJ.

The tests are carried out in accordance with IEC publication 60068. "Recommended basic climatic and mechanical robustness testing procedure for electronic components" and under standard atmospheric conditions according to "IEC 60068-1", subclause 5.3.

Unless otherwise specified the following values apply:

Temperature: 15 °C to 35 °C Relative humidity: 25% to 75%

Air pressure: 86 kPa to 106 kPa (860 mbar to 1060 mbar).

In Table 4 the tests and requirements are listed with reference to the relevant clauses of "IEC publications 60115-8 and 60068"; a short description of the test procedure is also given. In some instances deviations from the IEC recommendations were necessary for our method of specifying.

All soldering tests are performed with mildly activated flux.

Table 4 Test procedures and requirements

IEC	- ` 60.068-2			REQUIREMENTS			
60115-8 CLAUSE	60068-2 TEST METHOD	TEST	PROCEDURE RC01		RC02H	RC21	RC22H
Tests in a	ccordance	with the schedule	of IEC publication 60115-8				
4.4.1		visual examination no holes; clean surface			ce; no visible dam	age	
4.5		resistance	applied voltage (+0/–10%): $R < 10 \ \Omega : 0.1 \ V$ $10 \ \Omega \le R < 100 \ \Omega : 0.3 \ V$ $100 \ \Omega \le R < 1 \ k\Omega : 1 \ V$ $1 \ k\Omega \le R < 10 \ k\Omega : 3 \ V$ $10 \ k\Omega \le R < 100 \ k\Omega : 10 \ V$ $100 \ k\Omega \le R < 100 \ k\Omega : 25 \ V$ $R \ge 1 \ M\Omega : 50 \ V$	R – R _{nom} : max. ±5%	R – R _{nom} : max. ±1%	R – R _{nom} : max. ±5%	R – R _{nom} : max. ±1%
4.18	20 (Tb)	resistance to soldering heat	unmounted chips; 10 ±1 s; 260 ±5 °C	no visible damage $\Delta R/R \text{ max.: } \pm (0.5\% + 0.05 \ \Omega)$			
4.29	45 (Xa)	component solvent resistance	isopropyl alcohol or H₂O followed by brushing in accordance with "MIL 202 F"	no visible damage			
4.17	20 (Ta)	solderability	unmounted chips completely immersed for 2 ±0.5 s in a solder bath at 235 ±2 °C	good tinning (≥95% covered); no visible damage			amage

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IEC	IEC				REQUIR	EMENTS	
60115-8 CLAUSE	60068-2 TEST METHOD	TEST	PROCEDURE	RC01	RC02H	RC21	RC22H
4.7		voltage proof on insulation	maximum voltage (RMS) during 1 minute, metal block method		no breakdow	n or flashover	
4.13		short time overload	room temperature; P = $6.25 \times P_n$; 5 s (V $\leq 2 \times V_{max}$)		Δ R/R max.: ±	:(1% +0.05 Ω)	
4.33		bending	resistors mounted on a 90 mm		no visible	damage	
			glass epoxy resin PCB (FR4), bending RC01/02: 2 mm bending RC21/22: 3 mm.	Δ R/R max.: \pm (1% +0.05 Ω)	Δ R/R max.: $\pm (0.5\% + 0.05 \Omega)$	Δ R/R max.: \pm (1% +0.05 Ω)	Δ R/R max.: $\pm (0.5\% +0.05 \Omega)$
4.19	14 (Na)	rapid change of	30 minutes at LCT and		no visible	e damage	
		temperature	30 minutes at UCT; 5 cycles		Δ R/R max.: ±(0.5% +0.05 Ω)	
4.24.2	3 (Ca)	damp heat (steady state)	56 days; 40 ±2 °C; 93 +2/-3% RH; loaded with 0.01 P _n :				
			R ≤ 1 MΩ	Δ R/R max.: ±(1.5% +0.1 Ω)	Δ R/R max.: ±(1.0% +0.05 Ω)	Δ R/R max.: \pm (1.5% +0.1 Ω)	Δ R/R max.: ±(1.0% +0.05 Ω)
			R > 1 MΩ	Δ R/R max.: ± (3.0% +0.1 Ω)	Δ R/R max.: \pm (1.5% +0.05 Ω)	Δ R/R max.: $\pm (3.0\% + 0.1 \Omega)$	Δ R/R max.: ±(1.5% +0.05 Ω)
4.25.1		endurance	1000 +48/ $-$ 0 hours; 70 \pm 2 °C; loaded with P _n or V _{max} ; 1.5 hours on and 0.5 hours off:				
			R ≤ 1 MΩ	Δ R/R max.: ±(1.5% +0.1 Ω)	Δ R/R max.: ±(1.0% +0.05 Ω)	Δ R/R max.: ±(1.5% +0.1 Ω)	Δ R/R max.: ±(1.0% +0.05 Ω)
			R > 1 MΩ	Δ R/R max.: ± (3.0% +0.1 Ω)	Δ R/R max.: \pm (1.5% +0.05 Ω)	Δ R/R max.: $\pm (3.0\% + 0.1 \Omega)$	Δ R/R max.: ±(1.5% +0.05 Ω)
4.23.2	27 (Ba)	endurance at	1000 +48/-0 hours; no load:				
	upper category temperature		R ≤ 1 MΩ	Δ R/R max.: ±(1.5% +0.1 Ω)	Δ R/R max.: \pm (1.0% +0.05 Ω)	Δ R/R max.: \pm (1.5% +0.1 Ω)	Δ R/R max.: ±(1.0% +0.05 Ω)
			R > 1 MΩ	Δ R/R max.: ± (3.0% +0.1 Ω)	Δ R/R max.: \pm (1.5% +0.05 Ω)	Δ R/R max.: $\pm (3.0\% +0.1 \Omega)$	Δ R/R max.: $\pm (1.5\% +0.05 \Omega)$

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IEC	IEC			REQUIREMENTS			
60115-8 CLAUSE	60068-2 TEST METHOD	TEST	PROCEDURE	RC01	RC02H	RC21	RC22H
4.8.4.2		temperature coefficient	at 20/LCT/20 °C and 20/UCT/20 °C:				
			$1 \Omega \le R \le 10 \Omega$	≤250 ±250	≤250 ±250	≤250 ±250	≤250 ±250
			$10 \Omega < R \le 10 M\Omega$	≤±200	≤±100	≤±200	≤±100
Other test	s in accord	lance with IEC 601	15 clauses and IEC 60068 test m	ethod			
4.6.1.1		insulation resistance	voltage (DC) after 1 minute, metal block method	R_{ins} min.: 10^3 $M\Omega$			
4.12		noise	IEC publication 60195 (measured with Quantech - equipment):				
			R ≤ 100 Ω	max. 0.316 μV/V (–10 dB)			
			100 Ω < R ≤ 1 kΩ	max. 1 μV/V (0 dB)			
			1 kΩ < R ≤ 10 kΩ	max. 3 μV/V (9.54 dB)			
			10 kΩ < R ≤ 100 kΩ	max. 6 μV/V (15.56 dB)			
			100 kΩ < R ≤ 1 MΩ	max. 10 μV/V (20 dB)			
			$1 \text{ M}\Omega < R \le 10 \text{ M}\Omega$	max. 32 μV/V	(30.10 dB)		

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IEC	IEC			REQUIREMENTS			
60115-8 CLAUSE	60068-2 TEST METHOD	TEST	PROCEDURE	RC01	RC02H	RC21	RC22H
Other app	olicable test	ts					
(JIS) C 5202 7.9		resistance to damp heat (steady state)	1000 +48/ $-$ 0 hours; 40 \pm 2 °C; 93 +2/ $-$ 3% RH; loaded with P _n or V _{max} ; 1.5 hours on and 0.5 hours off:				
			R ≤ 1 MΩ	Δ R/R max.: \pm (3% +0.1 Ω)	Δ R/R max.: ±(2% +0.1 Ω)	Δ R/R max.: \pm (3% +0.1 Ω)	Δ R/R max.: \pm (2% +0.1 Ω)
			R > 1 MΩ	Δ R/R max.: ±(5% +0.1 Ω)	Δ R/R max.: ±(3% +0.1 Ω)	Δ R/R max.: \pm (5% +0.1 Ω)	Δ R/R max.: ±(3% +0.1 Ω)
EIA/IS 703 4.5		load humidity	1000 +48/–0 hours; 85 ±2 °C; 85 ±5% RH; loaded with 0.01 P _n or V _{max} :				
			R ≤ 1 MΩ	Δ R/R max.: \pm (3% +0.1 Ω)	Δ R/R max.: ±(2% +0.1 Ω)	Δ R/R max.: \pm (3% +0.1 Ω)	Δ R/R max.: \pm (2% +0.1 Ω)
			R > 1 MΩ	Δ R/R max.: \pm (5% +0.1 Ω)	Δ R/R max.: ±(3% +0.1 Ω)	Δ R/R max.: \pm (5% +0.1 Ω)	Δ R/R max.: ±(3% +0.1 Ω)
		shock termination test	-40 °C/+150 °C; 30 s on/30 s off; 500 cycles	no visual damag	e		

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REVISION HISTORY

Revision	Date	Change Notification	Description
Rev.3	2001 Apr 27	_	- Converted to Phycomp brand
Rev.4	2001 Oct 14	_	- Table 3: 'length' and 'width' changed; Table 4: 'bending' changed